

Title (en)
MAGNETRON SPUTTERING DEVICE

Title (de)
MAGNETRONSPUTTERVORRICHTUNG

Title (fr)
DISPOSITIF DE PULVÉRISATION CATHODIQUE À MAGNÉTRON

Publication
EP 3768871 A1 20210127 (DE)

Application
EP 19720848 A 20190429

Priority
• DE 102018112335 A 20180523
• EP 2019060913 W 20190429

Abstract (en)
[origin: WO2019223959A1] The invention relates to a magnetron sputtering device (100) which has: a substrate (20) a target (16) which forms a cathode (30) in an electric DC field and has an electrically conductive material mixture (36) for coating the substrate (20); an anode (34) in the electric DC field; a reaction chamber (10) in which the target (16) and the substrate (20) are arranged, wherein the target (16) is arranged to be separated physically from the substrate (20); and a voltage source (26), which is set up to generate the electric DC field between the cathode (30) and the anode (34); wherein the material mixture (36) comprises a first material (38) and a second material (40), and wherein the substrate (20) comprises a third material (42), wherein the first material (38) is an electrically nonconductive solid, the second material (40) is an electrically conductive solid, and the third material (42) is an electrically conductive solid.

IPC 8 full level
C23C 14/34 (2006.01); **H01J 37/34** (2006.01)

CPC (source: EP US)
C23C 14/3414 (2013.01 - EP US); **C23C 14/3485** (2013.01 - EP US); **C23C 14/35** (2013.01 - US); **H01J 37/32733** (2013.01 - EP); **H01J 37/32752** (2013.01 - US); **H01J 37/32779** (2013.01 - EP); **H01J 37/3405** (2013.01 - EP US); **H01J 37/3417** (2013.01 - EP); **H01J 37/3429** (2013.01 - EP US); **H01J 37/3438** (2013.01 - EP); **H01J 37/3467** (2013.01 - EP US); **H01J 2237/20214** (2013.01 - US)

Citation (search report)
See references of WO 2019223959A1

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

DOCDB simple family (publication)
WO 2019223959 A1 20191128; CN 112154226 A 20201229; DE 102018112335 A1 20191128; EP 3768871 A1 20210127; JP 2021524884 A 20210916; JP 7168686 B2 20221109; MX 2020012423 A 20210209; US 2021050192 A1 20210218

DOCDB simple family (application)
EP 2019060913 W 20190429; CN 201980033865 A 20190429; DE 102018112335 A 20180523; EP 19720848 A 20190429; JP 2020565461 A 20190429; MX 2020012423 A 20190429; US 202017087781 A 20201103